

### **AMENDMENTS TO THE CLAIMS**

Please amend the claims as follows:

#### **Listing of Claims:**

Claim 1 (Currently Amended): A semiconductor device comprising:

a semiconductor chip comprising a magnetic element;

an enclosure which seals the semiconductor chip and has a base material and a cap material joined together via a sealing material; ~~and~~

substantially spherical magnetic substance particles which are interspersed in the base material and the cap material; and

a lead frame, the lead frame including:

a die pad on which the semiconductor chip is mounted;

an inner lead portion sealed by the enclosure, the inner lead portion having a stacked structure in which a plurality of conductive layers are stacked via insulating layers, and the plurality of conductive layers are electrically connected to corresponding external connection electrodes on the semiconductor chip by bonding wires; and

an outer lead portion leading out of the enclosure.

Claim 2 (Currently Amended): A semiconductor device comprising:

a semiconductor chip comprising a magnetic element;

an enclosure which seals the semiconductor chip and which has a base material and a cap material joined together via a sealing material; ~~and~~

a magnetic film provided on a chip side surface of the base material and on an inner surface of the cap material so as to surround the semiconductor chip; and

a lead frame, the lead frame including:

a die pad on which the semiconductor chip is mounted;

an inner lead portion sealed by the enclosure, the inner lead portion having a stacked structure in which a plurality of conductive layers are stacked via insulating layers, and the plurality of conductive layers are electrically connected to corresponding external connection electrodes on the semiconductor chip by bonding wires; and  
an outer lead portion leading out of the enclosure.

Claim 3 (Original): The semiconductor device according to claim 1, wherein the enclosure is a plastic package or a ceramic package.

Claim 4 (Original): The semiconductor device according to claim 2, wherein the enclosure is a ceramic package.

Claim 5 (Original): The semiconductor device according to claim 3, wherein the plastic package contains an epoxy resin or a silicone resin.

Claim 6 (Original): The semiconductor device according to claim 3, wherein the ceramic package contains at least one of  $\text{Al}_2\text{O}_3$ ,  $\text{AlN}$ , and  $\text{BeO}$ .

Claim 7 (Original): The semiconductor device according to claim 4, wherein the ceramic package contains at least one of  $\text{Al}_2\text{O}_3$ ,  $\text{AlN}$ , and  $\text{BeO}$ .

Claims 8-11 (Cancelled).

Claim 12 (Original): The semiconductor device according to claim 1, wherein the magnetic element is a tunnel magneto-resistance element.

Claim 13 (Original): The semiconductor device according to claim 2, wherein the magnetic element is a tunnel magneto-resistance element.

Claim 14 (Original): The semiconductor device according to claim 1, wherein each magnetic substance particle contains at least one of an insulator, an oxide, and a ferrite.

Claim 15 (Original): The semiconductor device according to claim 1, wherein each magnetic substance particle has a diameter of 20  $\mu\text{m}$  or less.

Claim 16 (Original): The semiconductor device according to claim 1, wherein the magnetic substance particles occupy 1 wt% or more of the enclosure.

Claim 17 (Currently Amended): A semiconductor device comprising:  
a semiconductor chip comprising a magnetic element;  
an enclosure which seals the ~~magnetic~~ semiconductor chip; and  
substantially spherical magnetic substance particles which are interspersed in the enclosure, the particles preventing magnetic shape anisotropy; and  
a lead frame, the lead frame including:  
a die pad on which the semiconductor chip is mounted;  
an inner lead portion sealed by the enclosure, the inner lead portion having a stacked structure in which a plurality of conductive layers are stacked via insulating layers, and the plurality of conductive layers are electrically connected to corresponding external connection electrodes on the semiconductor chip by bonding wires; and  
an outer lead portion leading out of the enclosure.

Claim 18 (Previously Presented): The semiconductor device according to claim 17, wherein the enclosure is a plastic package or a ceramic package.

Claim 19 (Previously Presented): The semiconductor device according to claim 17, wherein the magnetic element is a tunnel magneto-resistance element.

Claim 20 (Previously Presented): The semiconductor device according to claim 17, wherein each magnetic substance particle contains at least one of an insulator, an oxide, and a ferrite.